

## Claim Instructions

### Claim Status

At filing there were claims 1 - 18

In a 3/13/02 restriction, claims 1-12 were elected.

In an 8/8/02 amendment definiteness and functionality amendments were made to claims 1 and 7

With this amendment, claims 1 - 3 and claims 7 - 9 are cancelled, and the presented claims are now 19,4-6, 20,10-12 .

### Amending Instructions

Rewrite the content of claims 1,2 and 3 in independent form as new claim 19 as follows and thereafter cancel claims 1, 2 and 3.

1    19. In an array of conductive joints between signal pads on a surface of an integrated circuit  
2    member of a material having a first thermal responsiveness and corresponding  
3    contacts on an aligned wiring support member of a material having a second thermal  
4    responsiveness,  
5    the improvement comprising:  
6    an interface having first and second portions,  
7    said first portion of said interface containing an array of elongated conductive joint  
8        members each having a contacting area made up of a length contacting dimension and  
9        a width contacting dimension and with said length contacting dimension being longer  
10    than said width dimension , and,  
11    said second portion of said interface having a contacting area approximating the contacting  
12    area of said conductive joint members of said first portion, being so positioned to  
13    accommodate expansion mismatch stresses in said conductive joint members,being at least

14 one contacting area positioned orthogonally with respect to said common aligned  
15 direction, and being an elongated contact in contact with said surface and a circular contact in  
16 contact with said wiring support member for each member of said array.

Adjust the dependency of claim 4 from claim 1 to claim 19.

Adjust the dependency of claim 5 from claim 1 to claim 19.

Rewrite the content of claims 7,8 and 9 in independent form as new claim 20 as follows and  
thereafter cancel claims 7, 8 and 9.

1 20. An improvement in an array of conductive joints between pads on a surface of an  
2 integrated circuit member of a material having a first thermal expansion responsiveness and  
3 corresponding contacts on an aligned wiring support member of a material having a second  
4 thermal responsiveness,  
5 comprising in combination:  
6 an interface between said pads and said contacts, having first and second portions,  
7 said first portion of said interface containing an array of elongated conductive joint  
8 members each having a contacting area made up of a length contacting dimension and  
9 a width contacting dimension and with said length contacting dimension being longer  
10 than said width dimension,  
11 said array of conductive joint members each being oriented with said length contacting  
12 length dimension in a common direction, and,  
13 said second portion of said interface having a contacting area approximating the contacting  
14 area of said conductive joint members of said first portion and being so positioned to  
15 accommodate expansion mismatch stresses in said conductive joint members, being at least

16 one contacting area positioned orthogonally with respect to said common direction and is an  
17 elongated contact in contact with said surface and a circular contact in contact with said  
18 wiring support member for each member of said array.

Adjust the dependency of claim 10 from claim 9 to claim 20.

The application is considered to be in condition for allowance

Respectfully submitted

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